

IPS1031(S)(R)

INTELLIGENT POWER LOW SIDE SWITCH

Features

- Over temperature shutdown
- Over current shutdown
- Active clamp
- Low current & logic level input
- ESD protection
- Optimized Turn On/Off for EMI
- Diagnostic on the input current

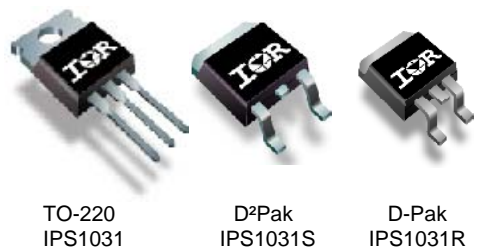
Description

The IPS1031(S)(R) is a three terminal Intelligent Power Switch (IPS) that features a low side MOSFET with over-current, over-temperature, ESD protection and drain to source active clamp. This device offers protections and the high reliability required in harsh environments. The switch provides efficient protection by turning OFF the power MOSFET when the temperature exceeds 165°C or when the drain current reaches 18A. The device restarts once the input is cycled. A serial resistance connected to the input provides the diagnostic. The avalanche capability is significantly enhanced by the active clamp and covers most inductive load demagnetizations.

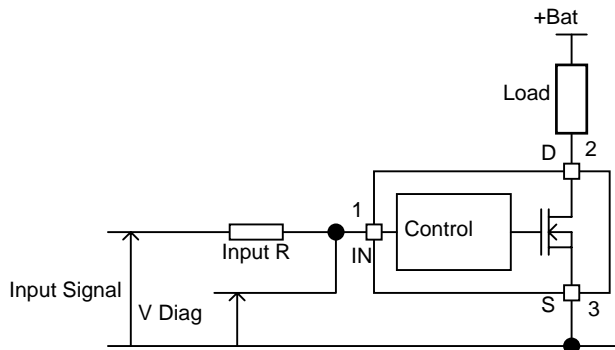
Product Summary

$R_{ds(on)}$	50m Ω (max.)
V_{clamp}	36V
$I_{shutdown}$	18A (typ.)

Packages



Typical Connection



Absolute Maximum Ratings

Absolute maximum ratings indicate sustained limits beyond which damage to the device may occur. All voltage parameters are referenced to Ground lead. (Tambient=25°C unless otherwise specified).

Symbol	Parameter	Min.	Max.	Units
Vds	Maximum drain to source voltage	-0.3	36	V
Vds cont.	Maximum continuous drain to source voltage	-	28	V
Vin	Maximum input voltage	-0.3	6	V
Isd cont.	Max. diode continuous current (limited by thermal dissipation)	—	4	A
Pd	Maximum power dissipation (internally limited by thermal protection)			
	Rth=5°C/W IPS1031	—	25	W
	Rth=40°C/W IPS1031S 1" sqr. footprint	—	3.1	
	Rth=50C/W IPS1031R 1" sqr. footprint	—	2.5	
ESD	Electrostatic discharge voltage (Human body) C=100pF, R=1500Ω			
	Between drain and source	—	4	kV
	Other combinations	—	3	
	Electrostatic discharge voltage (Machine Model) C=200pF, R=0Ω			
	Between drain and source	—	0.5	
	Other combinations	—	0.3	
Tj max.	Max. storage & operating temperature junction temperature	-40	150	°C
Tsoldering	Lead soldering temperature (10 seconds)	—	300	°C

Thermal Characteristics

Symbol	Parameter	Typ.	Max.	Units
Rth1	Thermal resistance junction to ambient IPS1031 TO-220 free air	50	—	°C/W
Rth2	Thermal resistance junction to case IPS1031 TO-220	3.9	—	
Rth1	Thermal resistance junction to ambient IPS1031S D²Pak std. footprint	60	—	
Rth2	Thermal resistance junction to ambient IPS1031S D²Pak 1" sqr. footprint	40	—	
Rth3	Thermal resistance junction to case IPS1031S D²Pak	3.9	—	
Rth1	Thermal resistance junction to ambient IPS1031R D-Pak std. footprint	70	—	
Rth2	Thermal resistance junction to ambient IPS1031R D-Pak 1" sqr. footprint	50	—	
Rth3	Thermal resistance junction to case IPS1031R D-Pak	3.9	—	

Recommended Operating Conditions

These values are given for a quick design. For operation outside these conditions, please consult the application notes.

Symbol	Parameter	Min.	Max.	Units
VIH	High level input voltage	4.5	5.5	
VIL	Low level input voltage	0	0.5	
Ids	Continuous drain current, Tambient=85°C, Tj=125°C, Vin=5V			A
	Rth=5°C/W IPS1031	—	9.5	
	Rth=40°C/W IPS1031S 1" sqr. footprint	—	3.3	
	Rth=50C/W IPS1031R 1" sqr. footprint	—	3	
Rin	Recommended resistor in series with IN pin to generate a diagnostic	0.5	10	kΩ
Max L	Max recommended load inductance (including line inductance) (1)	—	50	μH
Max F	Max. frequency (switching losses = conduction losses)	—	1.5	kHz
Max. t rise	Max. input rising time	—	1	μs

(1) Higher inductance is possible if maximum load current is limited - see figure 11

Static Electrical Characteristics

$T_j=25^{\circ}\text{C}$, $V_{cc}=14\text{V}$ (unless otherwise specified)

Symbol	Parameter	Min.	Typ.	Max.	Units	Test Conditions
Rds(on)	ON state resistance $T_j=25^{\circ}\text{C}$	—	40	50	m Ω	$V_{in}=5\text{V}$, $I_{ds}=8\text{A}$
	ON state resistance $T_j=150^{\circ}\text{C}$ (2)	—	76	95		
Idss1	Drain to source leakage current	—	0.1	10	μA	$V_{cc}=14\text{V}$, $T_j=25^{\circ}\text{C}$
Idss2	Drain to source leakage current	—	0.2	20		$V_{cc}=28\text{V}$, $T_j=25^{\circ}\text{C}$
V clamp1	Drain to source clamp voltage 1	36	39	—	V	$I_d=20\text{mA}$
V clamp2	Drain to source clamp voltage 2	—	40	42		$I_d=1\text{A}$
Vin clamp	IN to source pin clamp voltage	5.5	6.5	7.5		$I_{in}=1\text{mA}$
Vth	Input threshold voltage	—	1.7	—		$I_d=10\text{mA}$

Switching Electrical Characteristics

$V_{cc}=14\text{V}$, Resistive load= 1.5Ω , $R_{input}=0\Omega$, $V_{in}=5\text{V}$, $T_j=25^{\circ}\text{C}$

Symbol	Parameter	Min.	Typ.	Max.	Units	Test Conditions
Tdon	Turn-on delay time to 20%	3	10	30	μs	See figure 2
Tr	Rise time 20% to 80%	6	20	40		
Tdoff	Turn-off delay time to 80%	20	70	200		
Tf	Fall time 80% to 20%	6	15	30		
Eon + Eoff	Turn on and off energy	—	0.7	—	mJ	

Protection Characteristics

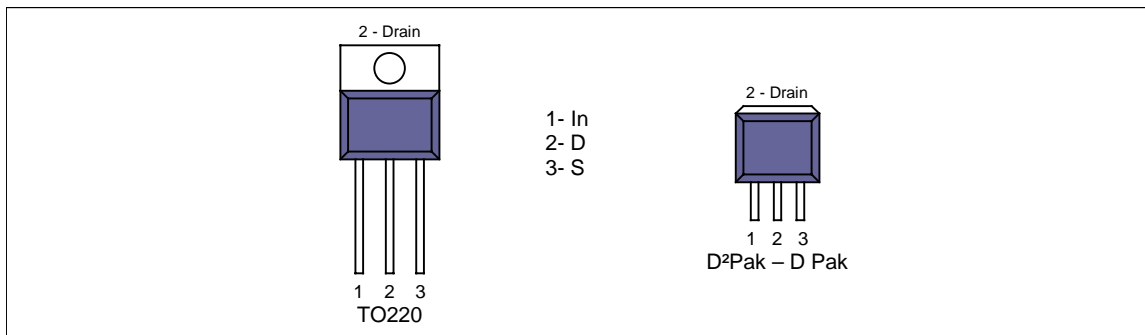
Symbol	Parameter	Min.	Typ.	Max.	Units	Test Conditions
Tsd	Over temperature threshold	150(2)	165	—	$^{\circ}\text{C}$	See figure 1
Isd	Over current threshold	12	18	24	A	See figure 1
OV	Over voltage protection (not active when the device is ON)	34	37	—	V	
Vreset	IN protection reset threshold	—	1.7	—	V	
Treset	Time to reset protection	15(2)	50	200	μs	$V_{in}=0\text{V}$

Diagnostic

Symbol	Parameter	Min.	Typ.	Max.	Units	Test Conditions
Iin, on	ON state IN positive current	15	32	70	μA	$V_{in}=5\text{V}$
Iin, off	OFF state IN positive current (after protection latched)	150	230	350		$V_{in}=5\text{V}$

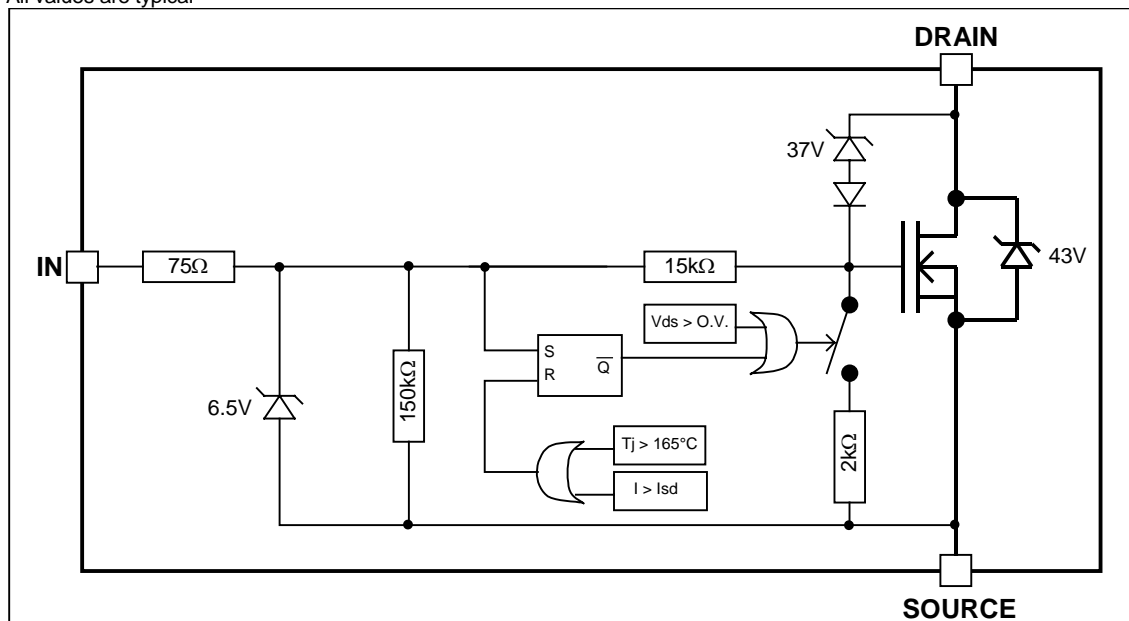
(2) Guaranteed by design

Lead Assignments



Functional Block Diagram

All values are typical



All curves are typical values. Operating in the shaded area is not recommended.

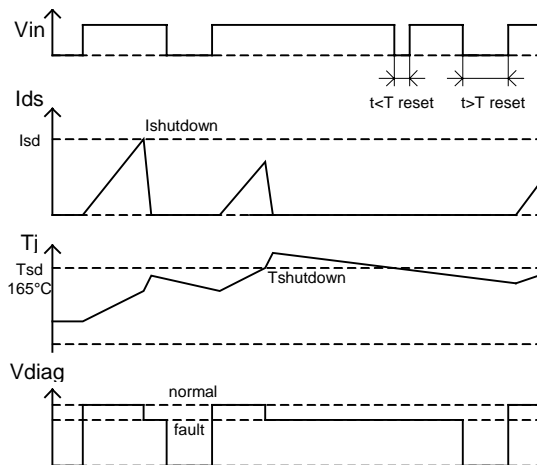


Figure 1 – Timing diagram

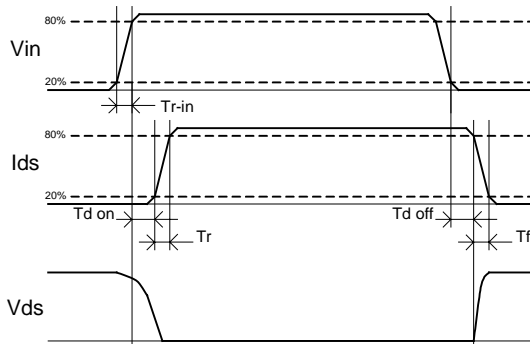


Figure 2 – IN rise time & switching definitions

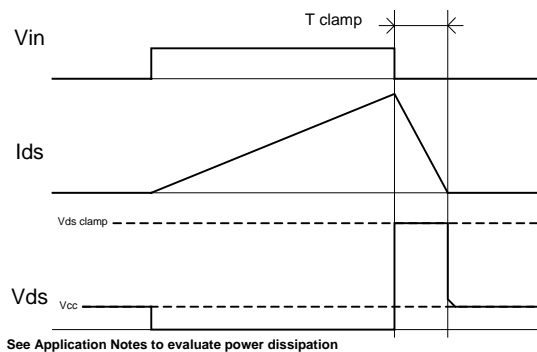


Figure 3 – Active clamp waveforms

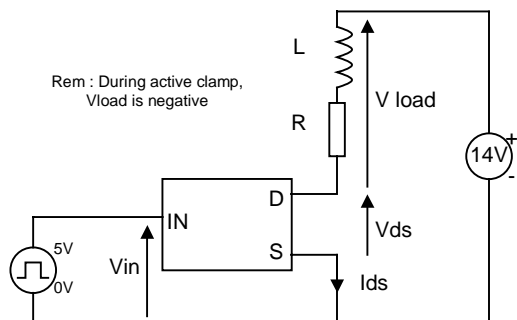


Figure 4 – Active clamp test circuit

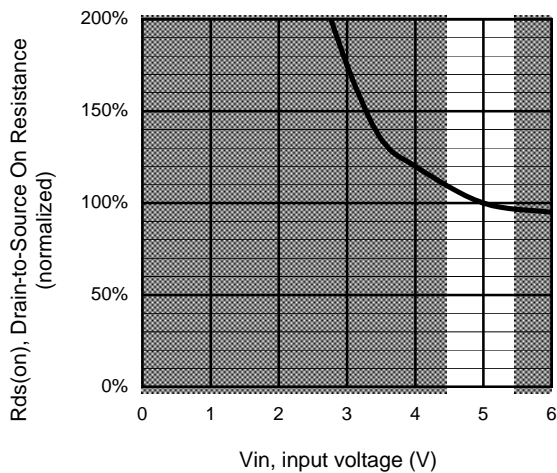


Figure 5 – Normalized R_{ds(on)} (%) Vs Input voltage (V)

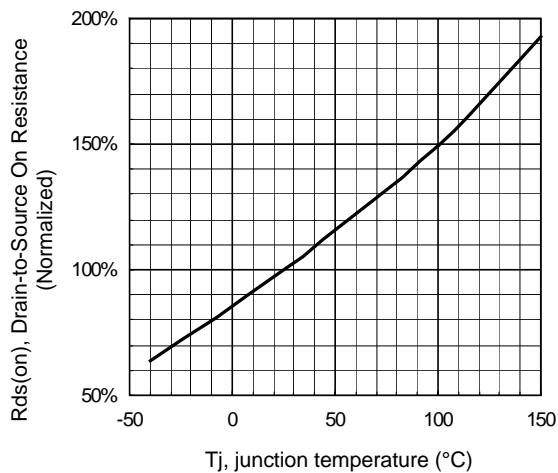


Figure 6 - Normalized R_{ds(on)} (%) Vs T_j (°C)

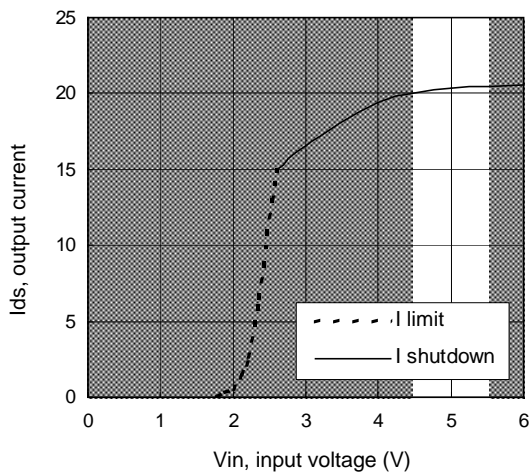


Figure 7 – Current limitation and current shutdown Vs Input voltage (V)

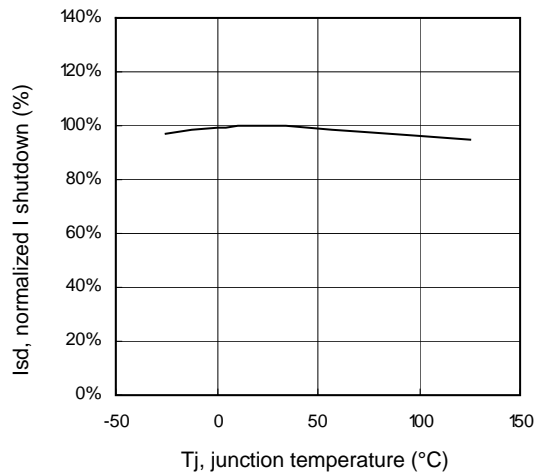
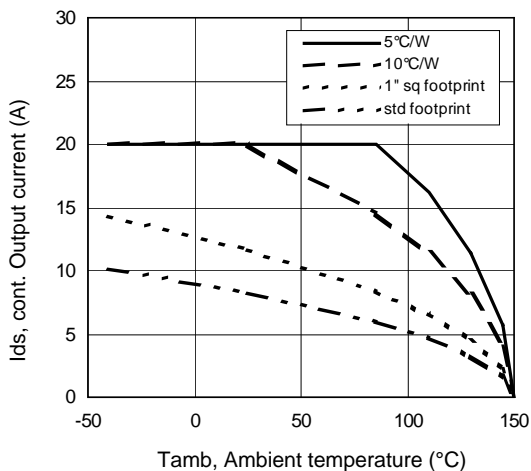
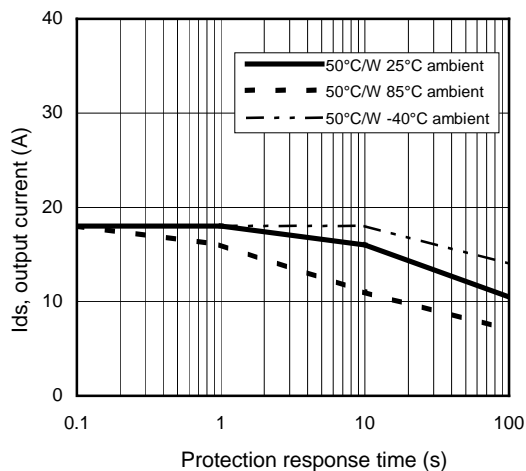


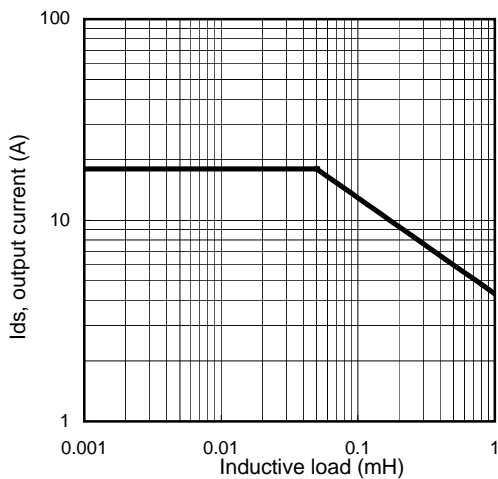
Figure 8 – Normalized I shutdown (%) Vs junction temperature (°C)



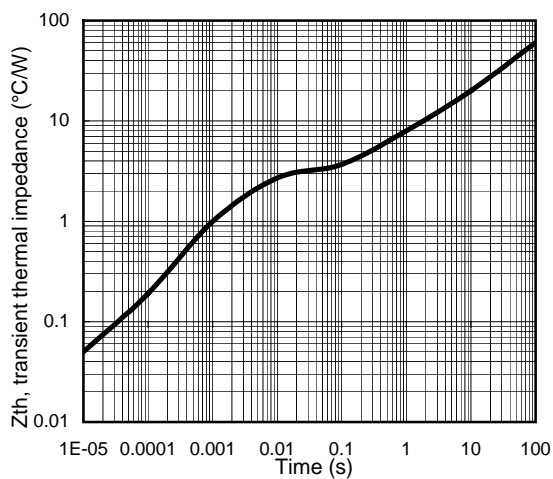
**Figure 9 – Max. continuous output current (A)
Vs Ambient temperature (°C)**



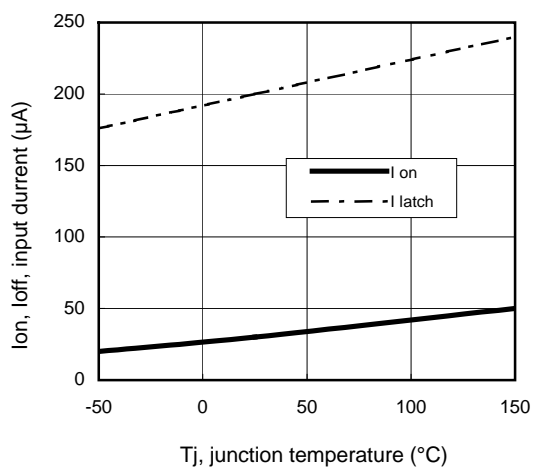
**Figure 10 – Ids (A) Vs over temperature
protection response time (s)**



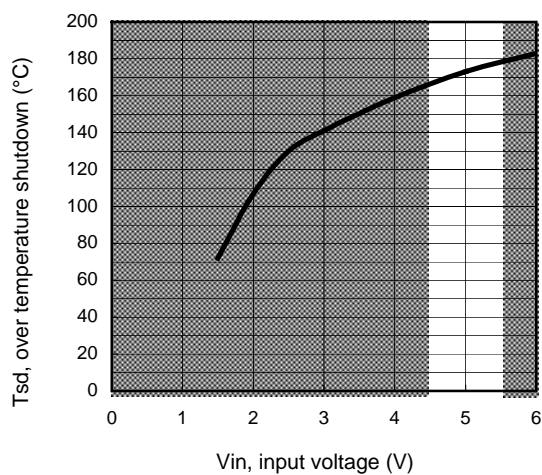
**Figure 11 – Max. output current (A)
Vs Inductive load (mH)**



**Figure 12 – Transient thermal impedance (°C/W)
Vs time (s)**

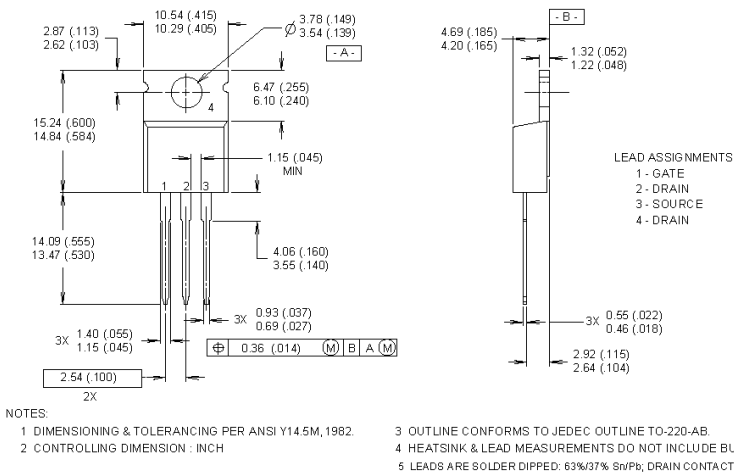


**Figure 13 – Input current (µA) On and Off
Vs junction temperature (°C)**

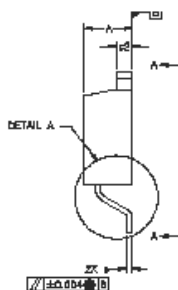
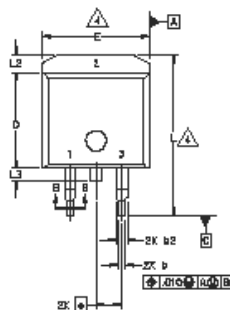
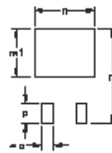
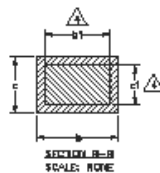
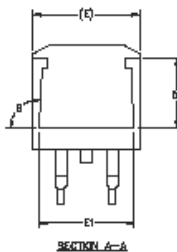
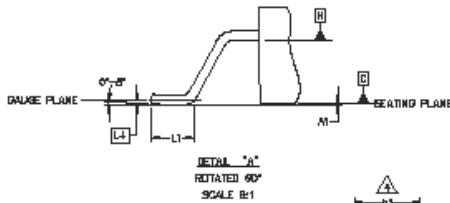


**Figure 14 – Over temperature shutdown (°C)
Vs input voltage (V)**

Case Outline – TO-220 AB



Case Outline - D²Pak (SMD-220)



S Y M B O L	D I M E N S I O N S				N O T E S
	M I L L I M E T E R S		I N C H E S		
	M I N .	M A X .	M I N .	M A X .	
A	4.06	4.83	.160	.190	4
A1		0.127		.005	
b	0.51	0.99	.020	.039	
b1	0.51	0.89	.020	.035	
b2	1.14	1.40	.045	.055	4
c	0.38	0.74	.015	.029	
c1	0.43	0.63	.017	.025	
c2	1.14	1.40	.045	.055	
D	8.51	9.85	.335	.380	3
D1	5.33		.210		
E	9.65	10.67	.380	.420	3
E1	6.22		.245		
e	2.54 BSC		.100 BSC		
L	14.61	15.88	.575	.625	
L1	1.78	2.79	.070	.110	
L2		1.65		.065	
L3	1.27	1.78	.050	.070	
L4	0.25 BSC		.010 BSC		
m	17.78		.700		
m1	8.89		.350		
n	11.43		.450		
a	2.08		.082		
p	3.81		.150		
θ	90°	93°	90°	93°	

LEAD ASSIGNMENTS

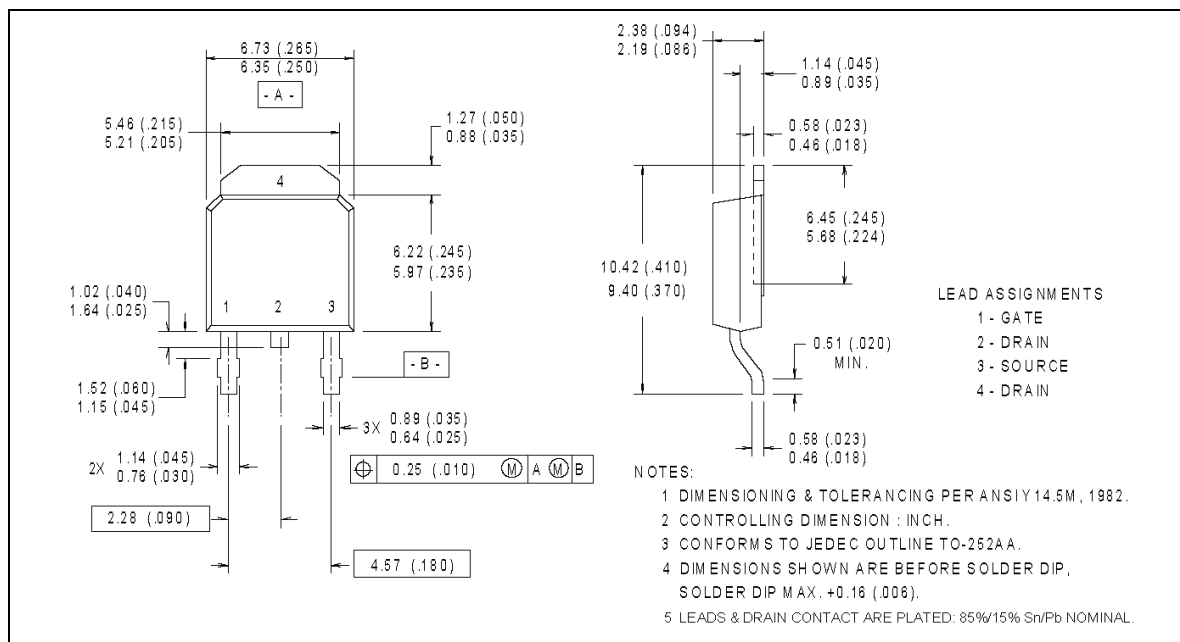
HEXFET	MBTA, D2PAK	MODES
1.- GATE	1.- GATE	1.- ANODE *
2.- DRAIN	2.- COLLECTOR	2.- CATHODE
3.- SOURCE	3.- EMITTER	3.- ANODE

* PART DEPENDENT.

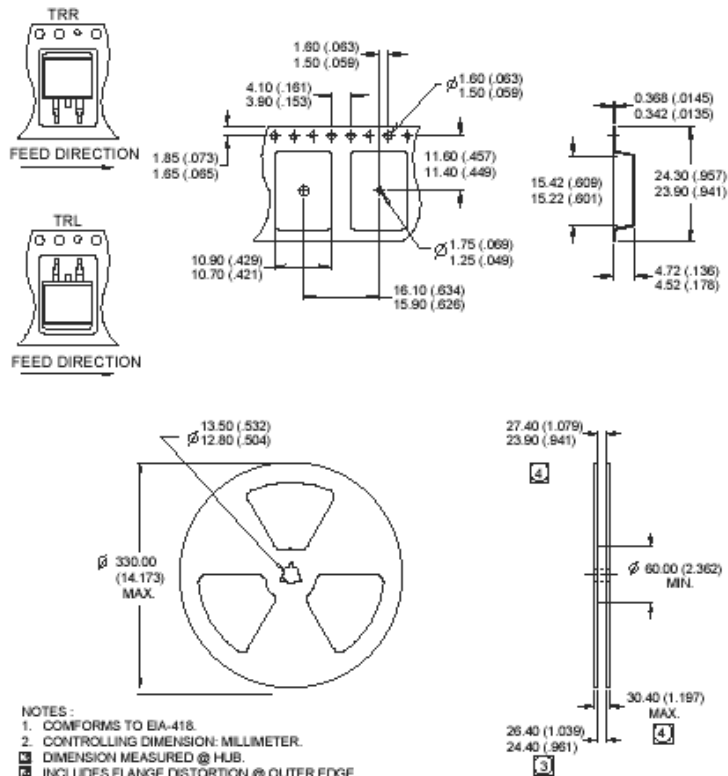
NOTES

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994
2. DIMENSIONS ARE SHOWN IN MILLIMETERS [INCHES].
3. DIMENSION D & E DO NOT INCLUDE MOLD FLASH. MOLD FLASH SHALL NOT EXCEED 0.127 [0.005] PER SIDE. THESE DIMENSIONS ARE MEASURED AT THE OUTMOST EXTREMES OF THE PLASTIC BODY.
4. DIMENSION b1 AND c1 APPLY TO BASE METAL ONLY.
5. CONTROLLING DIMENSION: INCH.

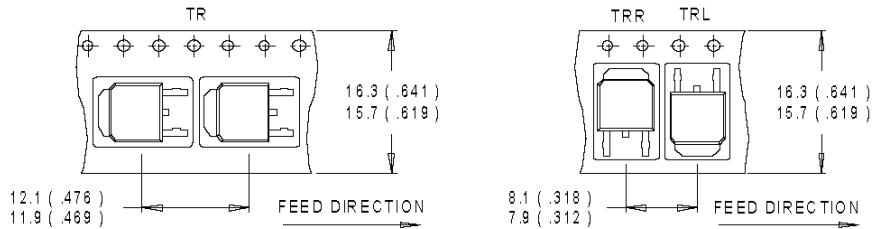
Case Outline – D-Pak



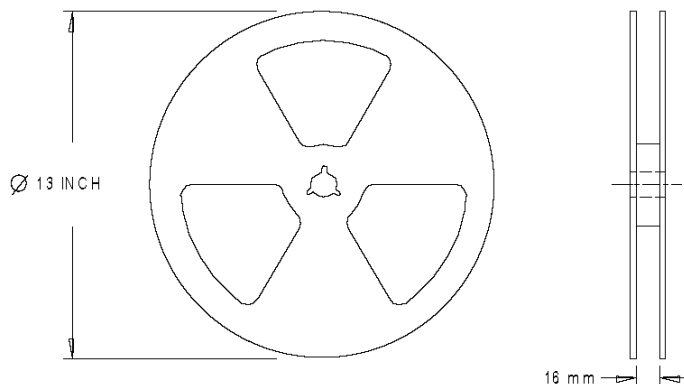
Tape & Reel - D²Pak (SMD220)



Tape & Reel - D-Pak



- NOTES :
1. CONTROLLING DIMENSION : MILLIMETER.
 2. ALL DIMENSIONS ARE SHOWN IN MILLIMETERS (INCHES).
 3. OUTLINE CONFORMS TO EIA-481 & EIA-541.



- NOTES :
1. OUTLINE CONFORMS TO EIA-481.

Dimensions are shown in millimeters (inches)